AMENDMENT TO CLAIMS

Please amend the claims as follows:

1. (Currently amended) A resin-encapsulated semiconductor device, comprising:

a die pad provided by removing a whole lower portion of a part of a lead frame that is to serve as the die pad;

a semiconductor chip mounted on the die pad;

a plurality of leads, each lead being provided by removing [[an]] a whole upper portion of a part of the lead frame that is to serve as the lead;

a connection member for connecting the semiconductor chip and the lead with each other;

a plurality of suspension leads connected to the die pad; and

an encapsulation resin for encapsulating therein the die pad, the semiconductor chip, the leads, the connection member and the suspension leads, with a bottom surface and an outer side surface of each lead being exposed as an external terminal, wherein:

an upper surface of the die pad is located higher than an upper surface of the lead;

a lower surface of the die pad is located higher than a lower surface of the lead; and

the suspension leads are not bent ~~in a bending process~~.

2. (Original) The resin-encapsulated semiconductor device of claim 1, wherein:

the semiconductor chip is mounted with its principal surface facing up; and

the connection member is a thin metal wire.

3. (Original) The resin-encapsulated semiconductor device of claim 1, wherein:

the semiconductor chip is mounted with its principal surface facing down; and

the connection member is a bump made of a metal.

4. (Original) The resin-encapsulated semiconductor device of claim 1, wherein at least a portion of the semiconductor chip overlaps with the lead as viewed from above.

5. (Original) The resin-encapsulated semiconductor device of claim 1, wherein at least a portion of each of the die pad and the lead has a thickness of 100 μm to 150 μm.

6-9. (Cancelled)

10. (Previously presented) The resin-encapsulated semiconductor device of claim 1, wherein a connecting portion of each of the suspension leads which is connected to the die pad is formed by removing the lower portion of the lead frame.